Hologram

Canada G2 – Triple cut form factor
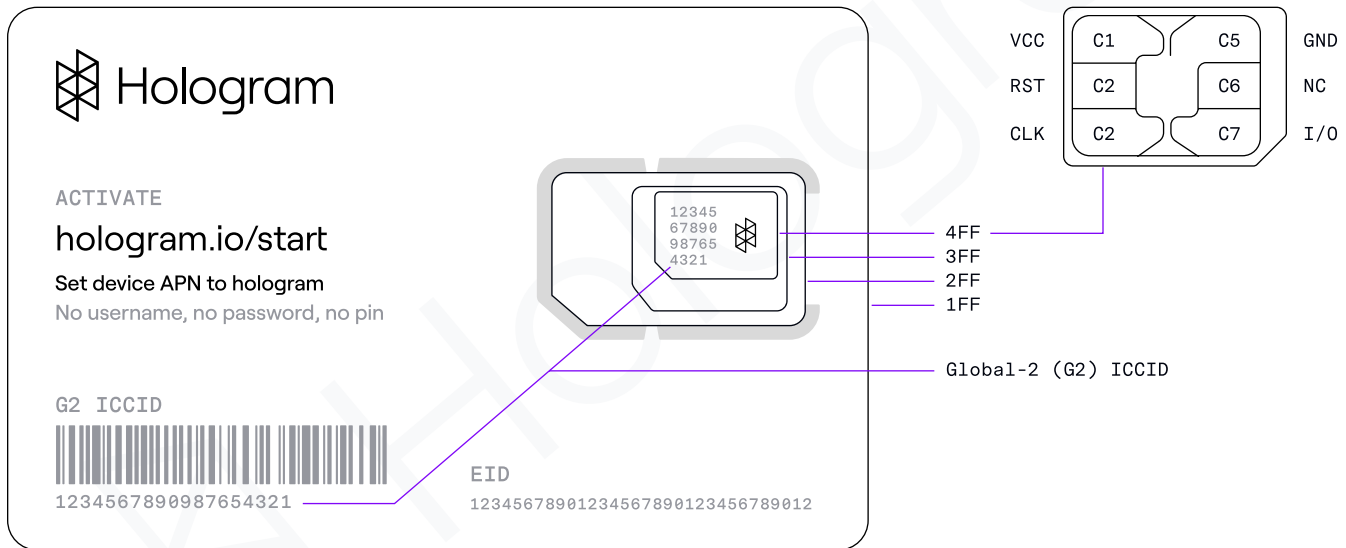
2FF, 3FF, 4FF

Product overview

A secure, device-agnostic IoT SIM card for deployments in Canada built for M2M data, with easy activation, transparent pricing, and developer-friendly tools. Hologram's Hyper SIMs are eUICC compliant and the Hyper platform remotely updates coverage over-the-air by adding or removing profiles, without requiring you to swap the SIM in your device.

Network availability

Works globally with Hologram's 2G through 4G (LTE) network including LTE-M and NB-IoT where coverage is available. More information: https://www.hologram.io/pricing/coverage

Part numbers

G2
G2-10
G2-100
G2-1000

Past part numbers

GL2
GL2-10
GL2-100
GL2-1000

Mechanical specifications

SIM card physical characteristics

Size

1FF	Full-size	85.6 × 54 × 0.71 mm
2FF	Mini-SIM	25 × 15 × 0.71 mm
3FF	Micro-SIM	15 × 12 × 0.71 mm
4FF	Nano-SIM	12.3 × 8.8 × 0.71 mm

Pin definitions

C1	VCC	Input Voltage
C2	RST	Reset
C3	CLK	Clock
C5	GND	Ground
C6	NC	No Connect
C7	I/O	Input/Output

Hardware features

Chip type

Supplier	Samsung
Chip Code	S3FW9FJM

Electrical

Operating Voltage	1.62V to 5.5V

Hardware characteristics

Grade	Standard
Operational Temperature	−25°C to +85°C
Data Retention	25 years @ 25°C
Write Endurance	500K cycles native, 10M cycles with High Endurance Interface @ 25°C
Memory (NVM)	704 KB
Memory (SRAM)	20 KB

AC electrical parameters standards

ETSI 3GPP TS 102 221 v14.0.0 - UICC–Terminal interface; Physical and logical characteristics
ISO/IEC 7816, T=0 standard for Cards with contacts — USB electrical interface and operating procedures

Compliance

Chip	Common Criteria	EAL 4+ CCN-CC-5/2019
OS	GSMA	Embedded UICC Technical Specification v3.2
	TCA TRUSTED CONNECTIVITY ALLIANCE	SIMalliance eUICC Profile Package Interoperable Format Technical Specification v2.3.1
	GLOBALPLATFORM®	Card Specification Version 2.1.1 Card Specification Version 2.2 Amendments A, B, D & E
Software	ORACLE Java Card	Java Card 3 Platform, Classic Edition version 3.0.5
	3GPP A GLOBAL INITIATIVE	Release 14
Remote SIM provisioning	GSMA	SGP.01 Embedded SIM Remote Provisioning Architecture v1.1 SGP.02 SGP.16 M2M Compliance Process v1.1
Supplier's Declaration of Conformity		Manufactured according to the following standards: • RoHS Directive 2011/65/EU • Reach certification • GSMA SAS-UP • ISO 9001:2015 • ISO 27001 • ISO 14001